

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"20050121757"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 17:38
L2	50178	(stiffener post) with (around surround\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 17:39
L3	55503	(stiffener post) with (around surround\$4 circl\$4 encircl\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 17:40
L4	5051	(chip die semiconductor flipchip (flip adj chip) element component ic (integrated adj circuit,, with 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 17:41
L5	484	(substrate carrier board pcb) with 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 17:41

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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L8	516216	(resin underfill\$4 under\$4 (under adj fill\$4) fillet epoxy encapsulat\$4 insulat\$4) with (different difference differ\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/05 23:44
L9	142959	tce (thermal with expansion with ((co adj efficient) coefficient))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/05 23:45
L10	7226	8 with 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/05 23:45
L11	1927	10 same ((semiconductor die chip flipchip (integrated adj circuit) ic element electronic component microelectronic) with (substrate carrier board pcb motherboard))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/05 23:46
L12	749	(surround\$4 encircle circle) and 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/05 23:47

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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	154144	cte tce (thermal with expansion with ((co adj efficient) coefficient))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 07:23
L8	1563612	(semiconductor die chip flipchip (integrated adj circuit) ic element electronic component microelectronic) with (substrate carrier board pcb motherboard)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 07:24
L9	1875918	th 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 07:24
L10	7396	(resin underfill\$4 under\$4 (under adj fill\$4) fillet epoxy encapsulat\$4 insulat\$4) with (differe...nt difference differ\$4) with 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 07:25
L11	54	(around circumference) same 10 same 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 07:25

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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	154144	cte tce (thermal with expansion with ((co adj efficient) coefficient))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 05:21
L2	133248	cte (thermal with expansion with ((co adj efficient) coefficient))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 05:21
L3	1563612	(semiconductor die chip flipchip (integrated adj circuit) ic element electronic component microelectronic) with (substrate carrier board pcb motherboard)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 05:22
L4	516216	(resin underfill\$4 under\$4 (under adj fill\$4) fillet epoxy encapsulat\$4 insulat\$4) with (different difference differ\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 05:23
L5	7356	4 with 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 05:23
L6	2016	5 same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 05:23
L7	800	(surround\$4 encircle circle) and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 05:24